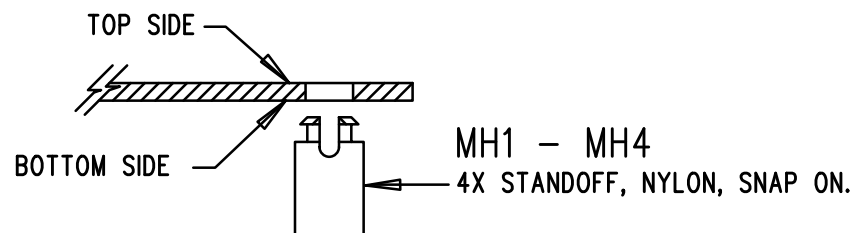


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	2ND PROTOTYPE	RYAN H.	03-05-14

APPROVALS

PCB DES. KIM T.

APP ENG. RYAN H.



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TITLE: TOP ASSEMBLY DRAWING

SMALL-SIZED PoE PD WITH POWER SUPPLY μMODULE

SIZE	IC NO. LT4275AIDD, LT4321IUF, LTM8027EV	REV.
N/A	DEMO CIRCUIT 2125A	2

SCALE = NONE

FILENAME: DC2125A-2.PCB

SHT 1 OF 2